

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S78	0	@ad<="20000627" and "438"/\$. ccls. and coaxial near3 hole near3 electrode	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 09:02
S79	22	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and coaxial same hole same electrode	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 09:23
S80	230	@ad<="20000627" and 257/E23. 011.ccls.	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 13:46
S81	972	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 (electrode metal\$4)	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 09:25
S82	169	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 (electrode metal\$4) near5 (wafer substrate)	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 10:10
S83	40	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 (electrode metal\$4) near5 (wafer substrate) and plurality near3 chip	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 10:41
S84	172	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 electrode and (dielectric insulat\$3) near2 electrode	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 10:42
S85	0	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 electrode and (deposit adj (dielectric insulat\$3) adj electrode)	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 10:43
S86	0	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 electrode and (deposit near2 (dielectric insulat\$3) adj electrode)	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 10:43
S87	2	@ad<="20000627" and ("438"/\$. ccls. "257"/\$.ccls.) and (through adj hole) near2 electrode and (dielectric insulat\$3) adj cover\$3 adj electrode	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:00

S88	0	@ad<="20000627" and plurality adj chip adj forming adj section	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:03
S89	25	@ad<="20000627" and plurality adj chip adj forming	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:10
S90	1	@pn="3969745"	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:04
S91	38	@ad<="20000627" and plurality adj chip near2 electrode	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:41
S92	1	@pn="5843821"	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:38
S93	49	@ad<="20000627" and (dry plasma) adj etch adj electrode	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:43
S94	87	@ad<="20000627" and (dry plasma) adj etch adj metal	US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB	OR	ON	2005/08/12 11:44